

LMNN3218SF 30V Dual N-Channel MOSFETs

Features

- 30V, 7.3A, $R_{DS(ON)}=22m\Omega@V_{GS}=10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available
- SOP-8 package design

Product Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been

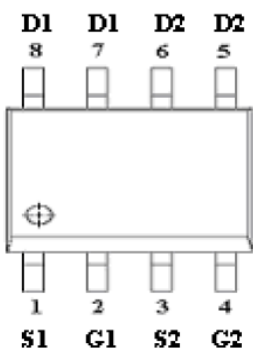
especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

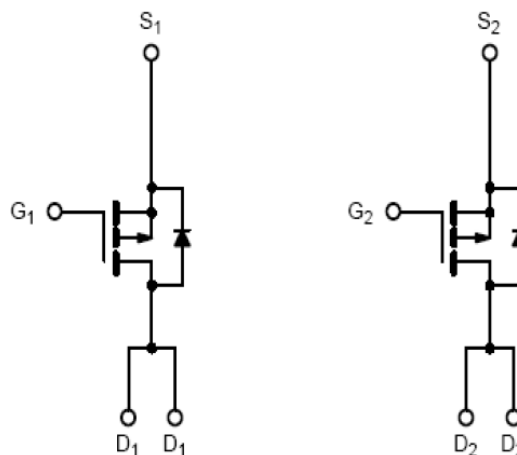
These devices are well suited for high efficiency fast switching applications.

Applications

- MB / VGA / Vcore
- POL Applications
- SMPS 2nd SR

Pin Configuration

LMNN3218SF (SOP-8)	
	
PIN	Description
1	Source 1
2	Gate 1
3	Source 2
4	Gate 2
5	Drain 2
6	Drain 2
7	Drain 1
8	Drain 1



Ordering Information

Ordering Information					
Part Number	P/N	PKG code	Pb Free code	Package	Quantity
LMNN3218SF	LMNN3218	S	F	SOP-8	4000pcs

Marking Information

Marking Information	
Part Number	LFC code
<u>3218S</u>	<u>XWMMMM</u>

Absolute Maximum Ratings

(T_C=25°C Unless otherwise noted)

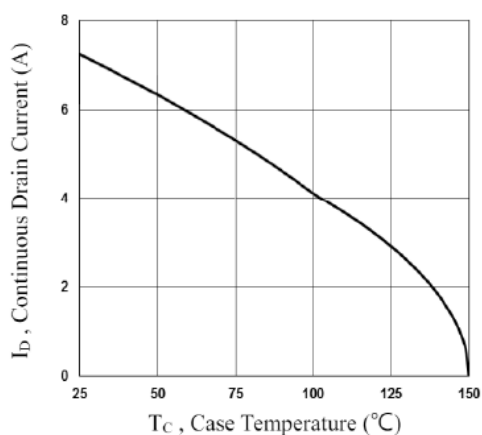
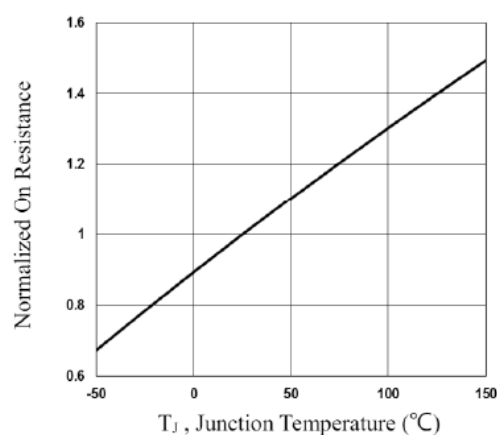
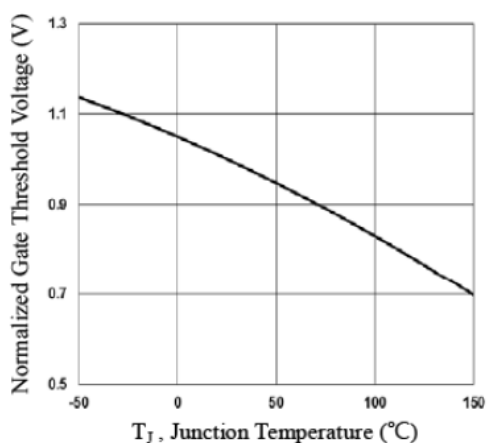
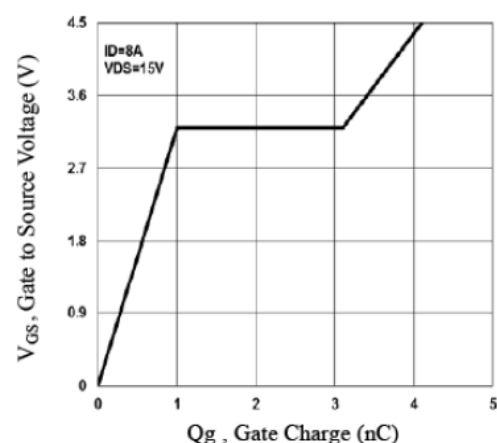
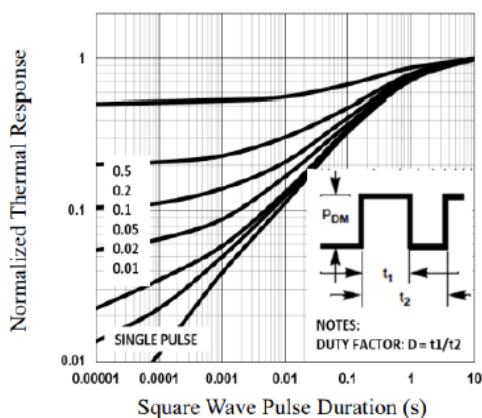
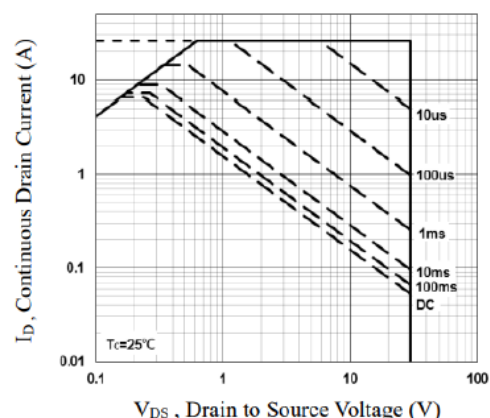
Symbol	Parameter	Typical	Unit
V _{DS}	Drain-Source Voltage	30	V
V _{GS}	Gate-Source Voltage	±20	V
I _D	Continuous Drain Current	T _A =25°C	A
		T _A =100°C	
I _{DM}	Pulsed Drain Current ¹	29	A
EAS	Single Pulse Avalanche Energy	32	mJ
IAS	Single Pulse Avalanche Current	8	A
P _D	Power Dissipation	T _A =25°C	W
		T _A =100°C	
T _J	Operating Junction Temperature	-55 to +150	°C
T _{STG}	Storage Temperature Range	-55 to +150	°C
R _{θJA}	Thermal Resistance-Junction to Case	70	°C/W

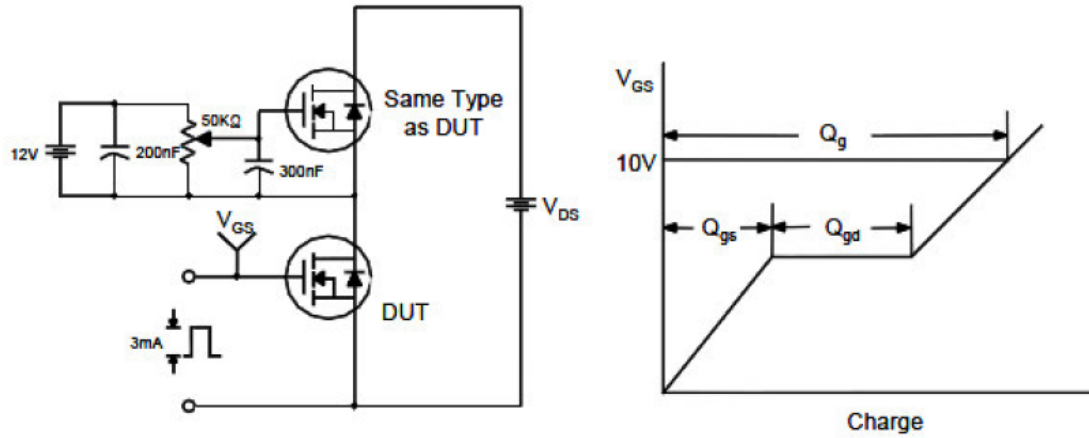
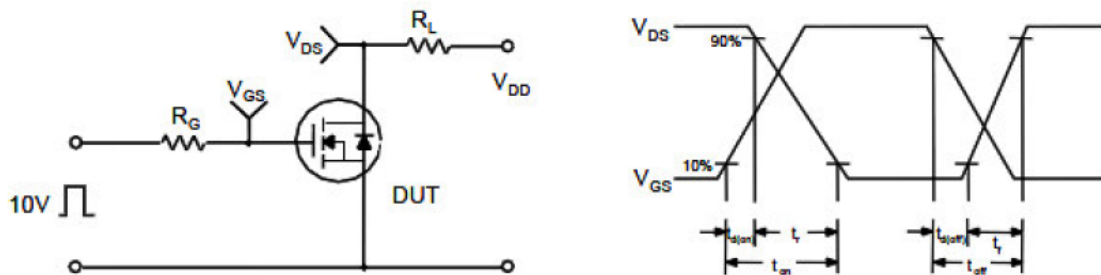
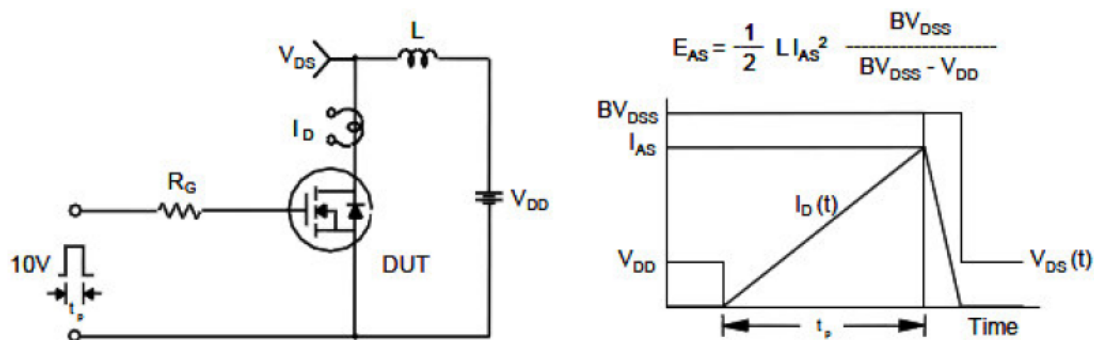
Electrical Characteristics

(T_C=25°C Unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	30			V
V _{GS (th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	1.2	1.6	2.5	V
I _{GSS}	Gate Leakage Current	V _{DS} =0V, V _{GS} =±20V			±100	nA
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V			1	uA
		V _{DS} =24V, V _{GS} =0V T _J =125°C			10	
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =0V			1	V
R _{DS(on)}	Drain-Source On-Resistance	V _{GS} =10V, I _D =7A		19	22	mΩ
		V _{GS} =4.5V, I _D =5A		24	28	
Dynamic characteristics						
Q _g	Total Gate Charge	V _{DD} =15V, V _{GS} =4.5V, I _D =7A		4.1	6	nC
Q _{gs}	Gate-Source Charge			1	1.4	
Q _{gd}	Gate-Drain Charge			2.1	4	
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, f=1.0MHz		345	500	pF
C _{oss}	Output Capacitance			55	80	
C _{rss}	Reverse Transfer Capacitance			32	45	
t _{d(on)}	Turn-On Time	V _{DD} =75V, V _{GS} =10V, R _g =10Ω, I _D =1.0A		2.8	5	ns
t _r				7.2	14	
t _{d(off)}	Turn-Off Time			15.8	30	
t _f				4.6	9	
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz		3.2	6.4	Ω

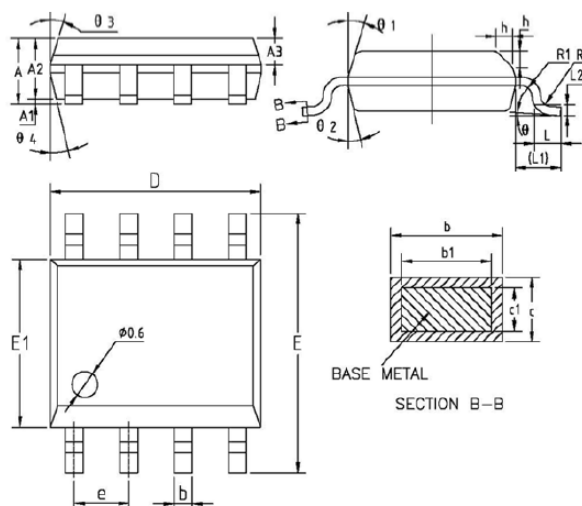
Typical Performance Characteristics


Fig.1 Continuous Drain Current vs. T_C

Fig.2 Normalized $R_{DS(on)}$ vs. T_J

Fig.3 Normalized V_{th} vs. T_J

Fig.4 Gate Charge Waveform

Fig.5 Normalized Transient Response

Fig.6 Maximum Safe Operation Area

Typical Performance Characteristics(continue)
Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveforms

Unclamped Inductive Switching Test Circuit & Waveforms


Package Dimension:

SOP-8



Dimensions				
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.531	0.689
A1	0.100	0.250	0.039	0.098
A2	1.250	1.650	0.492	0.650
A3	0.500	0.700	0.197	0.276
b	0.380	0.510	0.150	0.201
b1	0.370	0.470	0.146	0.185
c	0.180	0.250	0.071	0.098
c1	0.170	0.230	0.067	0.091
D	4.800	5.000	1.890	1.969
E	5.800	6.200	2.283	2.441
E1	3.800	4.000	1.496	1.575
e	1.170	1.370	0.461	0.539
L	0.450	0.800	0.177	0.315
L1	1.040 (BSC)		0.409 (BSC)	
L2	0.250 (BSC)		0.098 (BSC)	
R/R1	0.070	-	0.028	-
h	0.300	0.500	0.118	0.197
θ	0°	8°	0°	8°

NOTICE:

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